



# Application Note: SY8401

## High Efficiency, 1.2MHz, 55V Input, 0.8A Asynchronous Step Down Regulator

### General Description

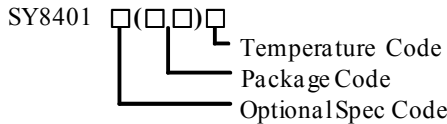
The SY8401 develops a high efficiency asynchronous step down DC/DC regulator capable of delivering 0.8A output current. The IC adopts current mode adaptive constant off time control. The SY8401 operates over a wide input voltage range from 4.5V to 55V and integrates main switch with very low  $R_{DS(ON)}$  to minimize the conduction loss.

Low output voltage ripple and small external inductor and capacitor sizes are achieved with 1.2MHz switching frequency.

### Features

- Low  $R_{DS(ON)}$  for Internal N-channel Power FET: 700m $\Omega$
- 4.5-55V Input Voltage Range
- 0.8A Output Current Capability
- 1.2MHz Pseudo Constant Switching Frequency
- Internal Soft-start Limits the Inrush Current
- Hic-cup Mode Output Short Circuit Protection
- EN ON/OFF Control with Accurate Threshold
- Cycle by Cycle Peak Current Limit
- 0.6V $\pm$ 1 % Reference Voltage
- SOT23-6 Package

### Ordering Information



Ordering Number	Package type	Note
SY8401ABC	SOT23-6	--

### Applications

- Non-Isolated Telecommunication Buck Regulator
- Secondary High Voltage Post Regulator
- Automotive Systems

### Typical Applications

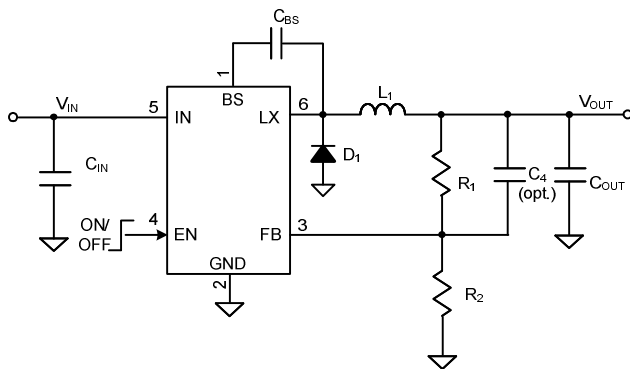


Figure 1. Schematic Diagram

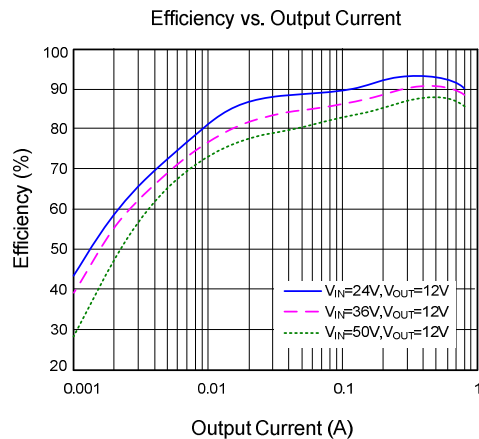
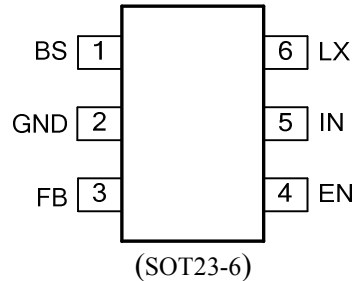


Figure 2. Efficiency

## Pinout (top view)



Top Mark: My xyz(Device code: My, x=year code, y=week code, z=lot number code)

Pin Name	Pin Number	Pin Description
BS	1	Boot-strap pin. Supply high side gate driver. Decouple this pin to the LX pin with a 0.1μF ceramic capacitor.
GND	2	Ground pin.
FB	3	Output feedback pin. Connect this pin to the center point of the output resistor divider (as shown in Figure 1) to program the output voltage: $V_{OUT}=0.6 \times (1+R1/R2)$ .
EN	4	Enable control. Pull high to turn on. Do not leave it floating.
IN	5	Input pin. Decouple this pin to the GND pin with at least a 1μF ceramic capacitor.
LX	6	Inductor pin. Connect this pin to the switching node of the inductor.

## Function Block

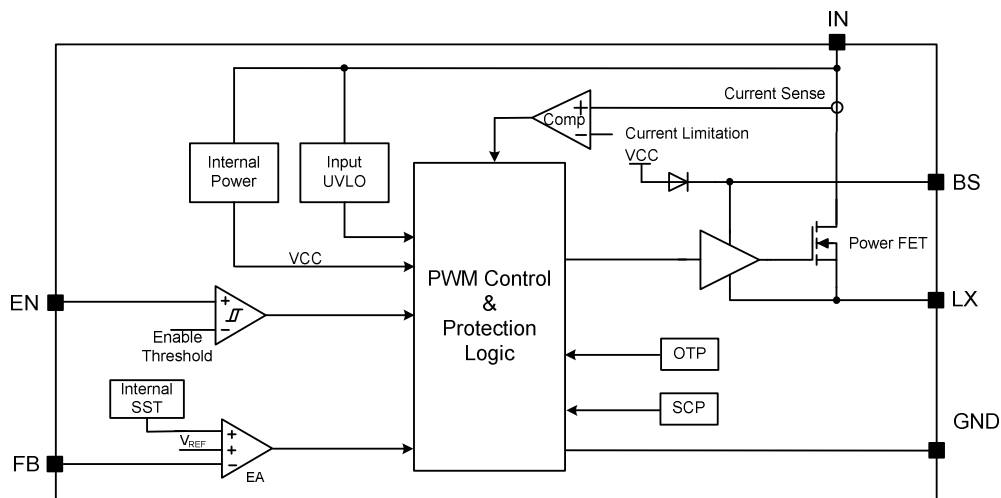


Figure3. Block Diagram



**Absolute Maximum Ratings** (Note 1)

Supply Input Voltage	-----60V
BS-LX	----- 4V
All other pins	----- $V_{IN} + 0.3V$
Power Dissipation, $P_D$ @ $T_A = 25^\circ C$ , SOT23-6,	----- 1W
Package Thermal Resistance (Note 2)	
$\theta_{JA}$	----- 100°C/W
$\theta_{JC}$	----- 25°C/W
Junction Temperature Range	----- 150°C
Lead Temperature (Soldering, 10 sec.)	----- 260°C
Storage Temperature Range	----- -65°C to 150°C

**Recommended Operating Conditions** (Note 3)

Supply Input Voltage	----- 4.5V to 55V
Junction Temperature Range	----- -40°C to 125°C
Ambient Temperature Range	----- -40°C to 85°C



## Electrical Characteristics

( $V_{IN} = 20V$ ,  $V_{OUT} = 12V$ ,  $L = 6.8\mu H$ ,  $C_{OUT} = 10\mu F$ ,  $T_A = 25^\circ C$ ,  $I_{OUT} = 0.1A$  unless otherwise specified)

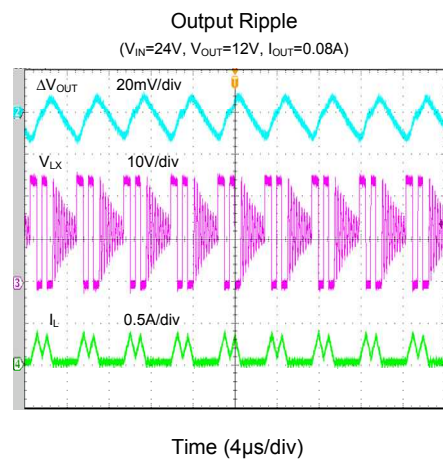
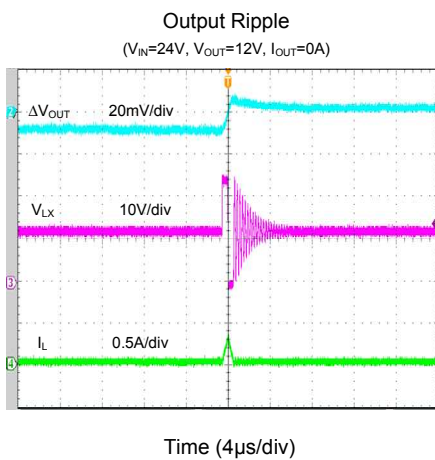
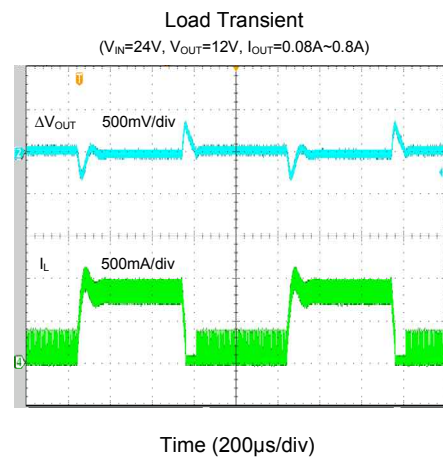
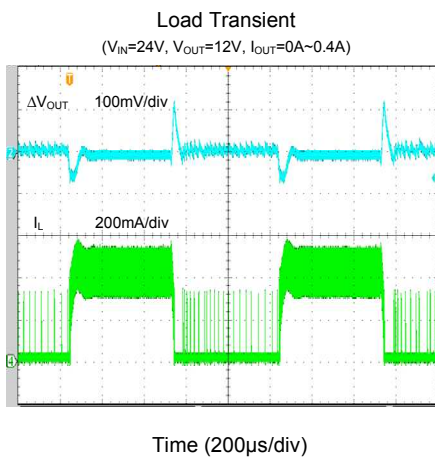
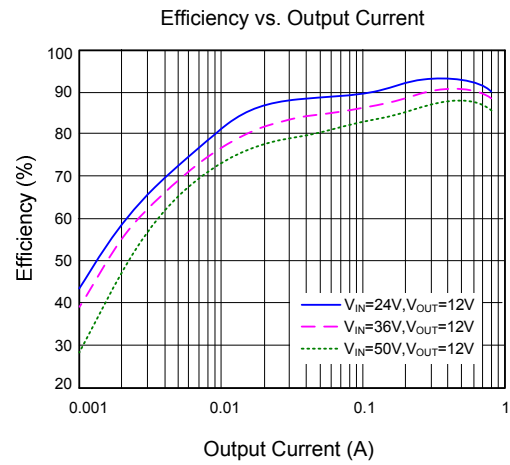
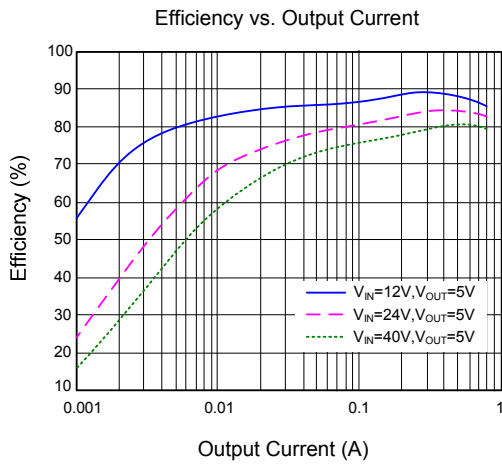
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage Range	$V_{IN}$		4.5		55	V
Quiescent Current	$I_Q$	LX not switching		150		$\mu A$
Shutdown Current	$I_{SHDN}$	EN=0		5	10	$\mu A$
Feedback Reference Voltage	$V_{REF}$		0.594	0.6	0.606	V
FB Input Current	$I_{FB}$	$V_{FB} = V_{IN}$	-50		50	nA
Power FET RON	$R_{DS(ON)}$			700		m $\Omega$
Power FET Peak Current Limit	$I_{LIM, TOP}$		1.05		1.65	A
EN Rising Threshold	$V_{ENH}$		1.18	1.23	1.28	V
EN Falling Threshold	$V_{ENL}$		0.94	1	1.06	V
Input UVLO Threshold	$V_{UVLO}$				4.5	V
Switching Frequency	$F_{SW}$			1.2		MHz
Switching Frequency Accuracy			-20		20	% $F_{SW}$
Min ON Time	$t_{ON}$			100		ns
Min Off Time	$t_{OFF}$			80		ns
Soft-start Time	$t_{SS}$			1.4		ms
Thermal Shutdown Temperature	$T_{SD}$			150		$^\circ C$
Thermal Shutdown Hysteresis	$T_{HYS}$			15		$^\circ C$

**Note 1:** Stresses beyond “Absolute Maximum Ratings” may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

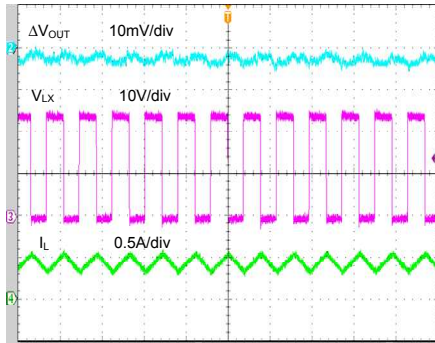
**Note 2:**  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25^\circ C$  on a high effective thermal conductivity four-layer test board per JESD51-7. Pin 2 of SOT23-6 package is the case position for  $\theta_{JC}$  measurement.

**Note 3:** The device is not guaranteed to function outside its operating conditions.

## Typical Performance Characteristics

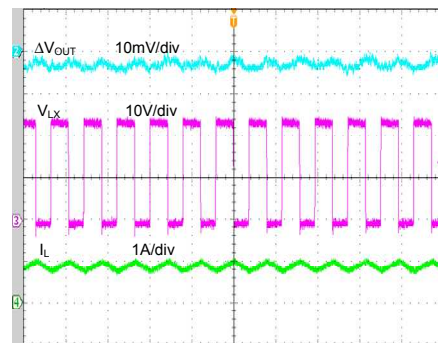


**Output Ripple**  
 ( $V_{IN}=24V, V_{OUT}=12V, I_{OUT}=0.4A$ )



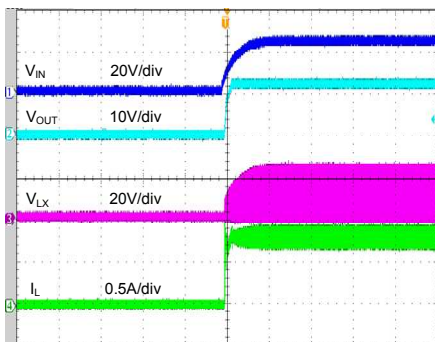
Time (1μs/div)

**Output Ripple**  
 ( $V_{IN}=24V, V_{OUT}=12V, I_{OUT}=0.8A$ )



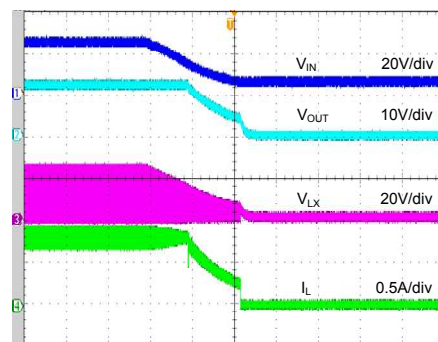
Time (1μs/div)

**Startup from  $V_{IN}$**   
 ( $V_{IN}=24V, V_{OUT}=12V, I_{OUT}=0.8A$ )



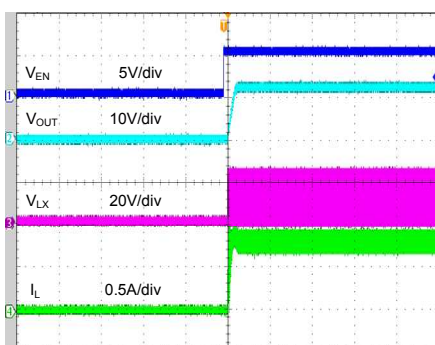
Time (10ms/div)

**Shutdown from  $V_{IN}$**   
 ( $V_{IN}=24V, V_{OUT}=12V, I_{OUT}=0.8A$ )



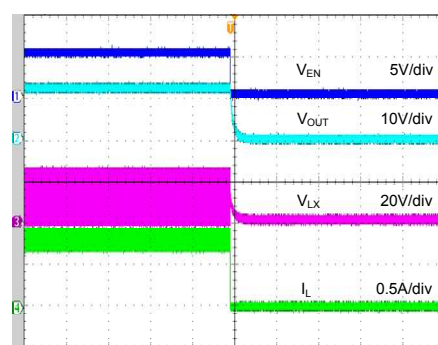
Time (4ms/div)

**Startup from Enable**  
 ( $V_{IN}=24V, V_{OUT}=12V, I_{OUT}=0.8A$ )



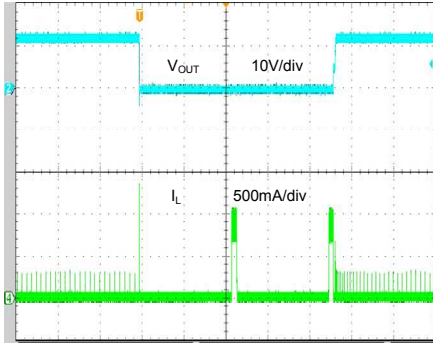
Time (4ms/div)

**Shutdown from Enable**  
 ( $V_{IN}=24V, V_{OUT}=12V, I_{OUT}=0.8A$ )



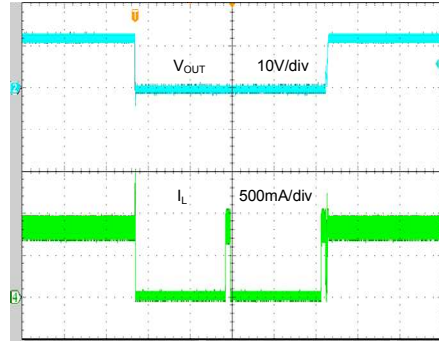
Time (4ms/div)

Short Circuit Protection  
( $V_{IN}=24V$ ,  $V_{OUT}=12V$ ,  $I_{OUT}=0A$ -Short)



Time (20ms/div)

Short Circuit Protection  
( $V_{IN}=24V$ ,  $V_{OUT}=12V$ ,  $I_{OUT}=0.8A$ -Short)



Time (20ms/div)

## Operation

The SY8401 develops a high efficiency asynchronous step down DC/DC regulator capable of delivering 0.8A output current. The device adopts current mode adaptive constant off time control. The SY8401 operates over a wide input voltage range from 4.5V to 55V and integrates main switch with very low  $R_{DS(ON)}$  to minimize the conduction loss.

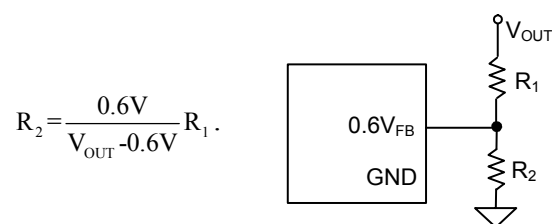
Low output voltage ripple and small external inductor and capacitor sizes are achieved with 1.2MHz switching frequency.

## Applications Information

Because of the high integration in the SY8401, the application circuit based on this IC is rather simple. Only the input capacitor  $C_{IN}$ , the output capacitor  $C_{OUT}$ , the output inductor  $L_1$  and the feedback resistors ( $R_1$  and  $R_2$ ) need to be selected for the targeted applications.

### Feedback Resistor Divider $R_1$ and $R_2$

Choose  $R_1$  and  $R_2$  to program the proper output voltage. To minimize the power consumption under light load, it is desirable to choose large resistance values for both  $R_1$  and  $R_2$ . A value between 10k $\Omega$  and 1M $\Omega$  is highly recommended for both resistors. If  $V_{OUT}$  is 1.2V,  $R_1=100k\Omega$  is chosen, then using the following equation,  $R_2$  can be calculated to be 100k $\Omega$ :



### Input Capacitor $C_{IN}$

The ripple current through the input capacitor is calculated as:

$$I_{CIN\_RMS} = I_{OUT} \times \sqrt{D(1-D)}$$

To minimize the potential noise problem, place a typical X5R or better grade ceramic capacitor really close to the IN and GND pins. Care should be taken to minimize the loop area formed by  $C_{IN}$  and IN/GND pins. In this case, a 10 $\mu$ F low ESR ceramic capacitor is recommended.

### Output Capacitor $C_{OUT}$

The output capacitor is selected to handle the output ripple noise requirements. Both steady state ripple and transient requirements must be taken into consideration when selecting this capacitor. For most applications, a X5R or better grade ceramic capacitor larger than 22 $\mu$ F capacitance can work well. The capacitance derating with DC voltage must be considered.

### Output Inductor $L_1$

There are several considerations in choosing this inductor.

- 1) Choose the inductance to provide the desired ripple current. It is suggested to choose the ripple current to be about 40% of the maximum output current. The inductance is calculated as:

$$L = \frac{V_{OUT}(1 - V_{OUT}/V_{IN,MAX})}{F_{SW} \times I_{OUT,MAX} \times 40\%}$$

where  $F_{sw}$  is the switching frequency and  $I_{OUT,MAX}$  is the maximum load current.

The SY8401 is quite tolerant of different ripple current amplitude. Consequently, the final choice of inductance can be slightly off the calculation value without significantly impacting the performance.

- 2) The saturation current rating of the inductor must be selected to be greater than the peak inductor current under full load conditions.

$$I_{SAT,MIN} > I_{OUT,MAX} + \frac{V_{OUT}(1 - V_{OUT}/V_{IN,MAX})}{2 \times F_{SW} \times L}$$

- 3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. It is desirable to choose an inductor with  $DCR < 50m\Omega$  to achieve a good overall efficiency.

### Enable Operation

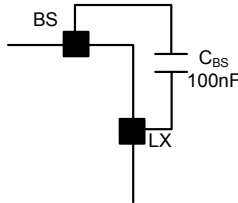
Pulling the EN pin low (<0.94V) will shutdown the device. During shutdown mode, the SY8401 shutdown current drops to lower than 10 $\mu$ A. Driving the EN pin high (>1.26V) will turn on the IC again.

### External Bootstrap Capacitor

This capacitor provides the gate driver voltage for internal high side MOSEFET. A 100nF low ESR



ceramic capacitor connected between the BS pin and the LX pin is recommended.



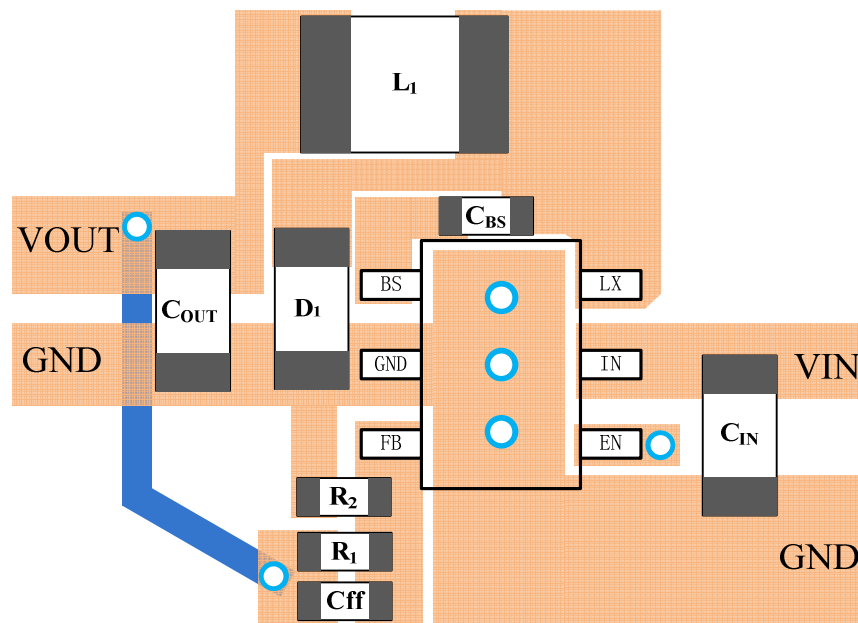
### Load Transient Considerations

The SY8401 integrates the compensation components to achieve good stability and fast transient responses. In some application, adding a 22pF ceramic capacitor in parallel with  $R_1$  may further speed up the load transient responses and is thus recommended for applications with large load transient step requirements.

### Layout Design

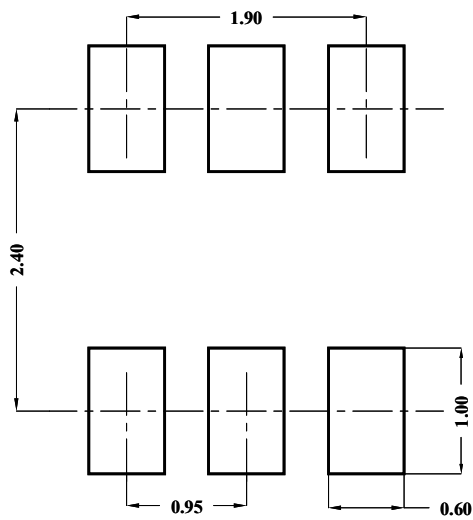
The layout design of the SY8401 is relatively simple. For the best efficiency and minimum noise problem, the following components should be placed close to the IC:  $C_{IN}$ ,  $L_1$ ,  $D_1$ ,  $R_1$  and  $R_2$ .

- 1) It is desirable to maximize the PCB copper area connecting to the GND pin to achieve the best thermal and noise performance. If the board space allows, a ground plane is highly desirable.
- 2)  $C_{IN}$  must be close to the IN and GND pins. The loop area formed by  $C_{IN}$  and GND must be minimized.
- 3) The PCB copper area associated with the LX pin must be minimized to avoid the potential noise problem.
- 4) The components  $R_1$  and  $R_2$  and the trace connecting to the FB pin must NOT be adjacent to the LX node on the PCB layout to avoid the noise problem.
- 5) If the system chip interfacing with the EN pin has a high impedance state at shutdown mode and the IN pin is connected directly to a power source such as a Li-Ion battery, it is desirable to add a pull down  $1M\Omega$  resistor between the EN and GND pins to prevent the noise from falsely turning on the regulator at shutdown mode.

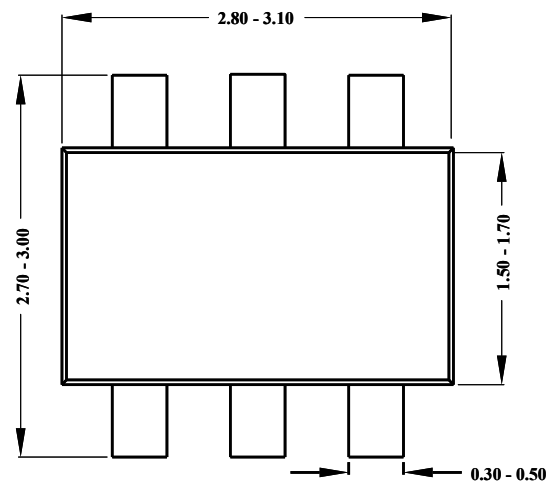


**Figure4. PCB Layout Suggestion**

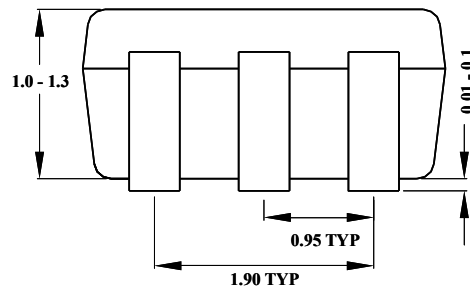
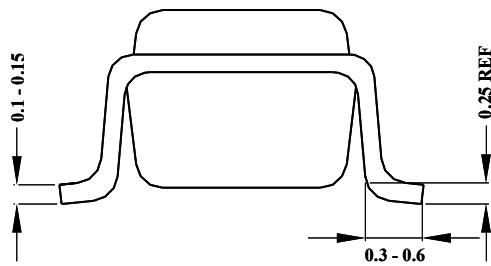
## SOT23-6 Package Outline & PCB layout



**Recommended Pad Layout**



**Top View**

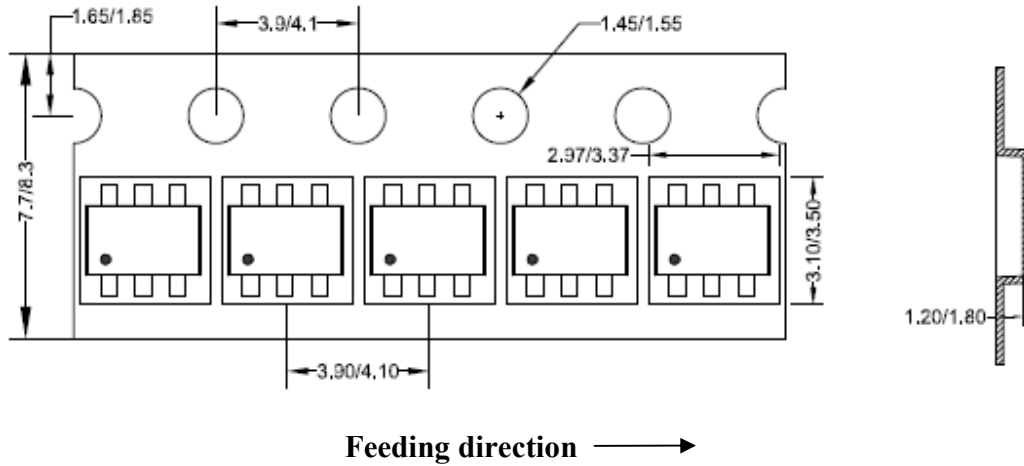


**Notes:** All dimension in millimeter and exclude mold flash & metal burr.

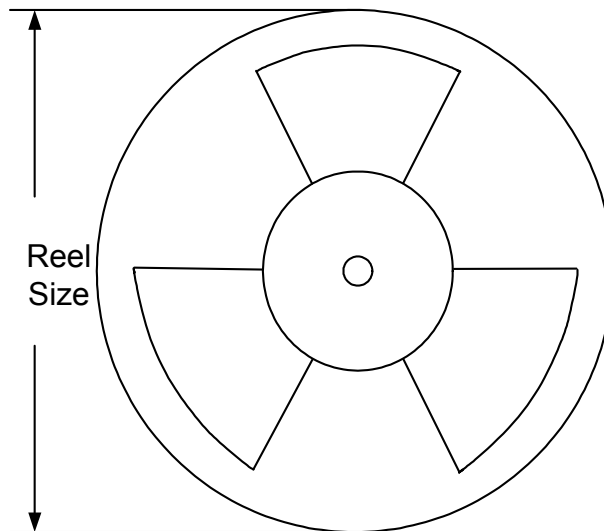
**Taping & Reel Specification**

**1. Taping orientation**

SOT23-6



**2. Carrier Tape & Reel specification for packages**



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
SOT23-6	8	4	7"	280	160	3000

**3. Others: NA**